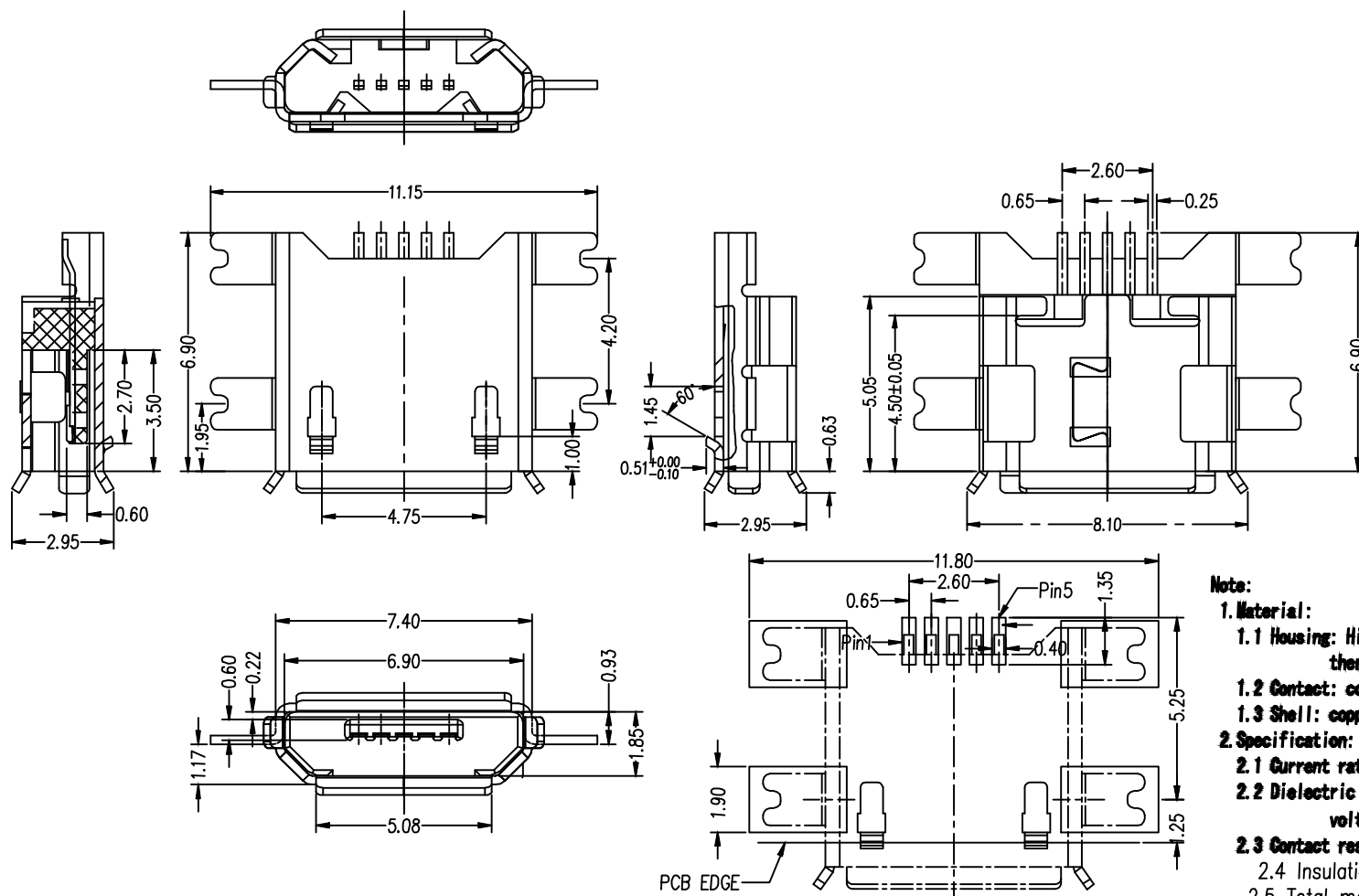




RECOMMENDED PCB LAYOUT

Note:

1. Material:

1.1 Housing: High temperature thermoplastic with g.f. UL94v-0

1.2 Contact: copper alloy, $t=0.20\text{mm}$

1.3 Shell: copper alloy, $t=0.25\text{mm}$

2. Specification:

2.1 Current rating: 1 A Max.

2.2 Dielectric withstanding

voltage: 100 V(ac) for 1 min.

2.3 Contact resistance: 50 mΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05

Kaf Min.after 3000 insertion/extraction cycles

2.7 Temperature range: $-30^{\circ}\text{C}\sim 80^{\circ}\text{C}$

GENERAL TOLERANCE		KINGCONN	皇海科技股份有限公司	
X± 0.50	X*± 5 *		Micro USB 5s B Type (破版式) Smt	
.X± 0.30	.X*± 2 *			
.XX± 0.20	.XX*± 1 *			
		名 称(TITLE)		
单 位(UNIT)	料 號(PART NO.)	圖 號(DWG NO.)		
mm	7MCUB-F0-0033	7MCUB-F0-0033		
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 率 SCALE	強 度 SHEET
			1:1	1 / 1
			 更改 REV	A

